



DEVICE TYPE:				<b>SEMPAC, INC.</b> Open-Pak™ Technologies <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006			
CUSTOMER:			DIE SIZE:				
WIRE TYPE/ SIZE:			NO. OF WIRES:				
THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	REVISIONS					16 Lead 4mm x 4mm MLP Open-Pak Bonding Diagram	
	ECN NO.	DATE	DESCRIPTION	APPROVED			
	10476	10/17/05	INITIAL RELEASE	D. BENANDO			
DRAWN BY	W. GRIFFITTS	DATE	10/17/05	PACKAGE SIZE:	4.00mm X 4.00mm	SIZE	A
APP BY	P. FLASKERUD	DATE	10/17/05	DIE PAD SIZE:	2.300mm x 2.300mm	PART NO.	MLP4X4-16-OP-01
				SCALE	36X	CAD FILE	MLP4X4-16-OP-01-B-R1.DWG
						SHEET	1 OF 1